

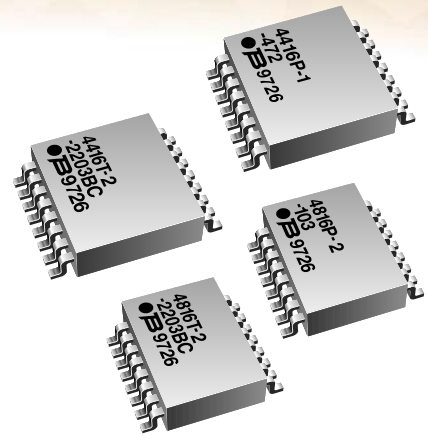


Product Change Notification

RESISTOR NETWORKS

August, 2007

Bourns Manufacturers Representatives
Corporate Distributor Product Managers
Americas Sales Team
Asia Sales Team
Europe Sales Team
Bourns Internal
Bourns Plant Managers



Surface Mount Networks Model Series 4400 & 4800 Terminal Finish Material Change

Effective with shipments beginning October 1, 2007 (date code C0740), we are making a running change to the terminal finish on the surface mount Resistor Network Model Series [4400P](#), [4800P](#), [4400T](#) and [4800T](#). The finish is applied after molding and forming of the terminals.

Currently the hot solder dip process uses a 96.5 % Sn 3 % Ag 0.5 % Cu alloy.

The new hot solder dip process will use a 99.3 % Sn 0.7 % Cu alloy.

Both alloys are backwards compatible with SnPb soldering processes.

As a result of the alloy change, the labeling on our RoHS page on our website and on the shipping label will also change in accordance with the industry “JEDEC STANDARD JESD97: Marking, Symbols and Labels for Identification of Lead (Pb) Free Assemblies, Components, and Devices”.

Terminal finish code:

Current marking: e1 – SnAgCu

After the change: e2 – Sn alloys with no Bi or Zn excluding SnAgCu

Note: All of the product in any package will contain the same finish process and will have the same “e” value applied.

[Wil Cantrell](#)

Product Line Manager

Specialty Resistor Products